

Electronic Patent Application Fee Transmittal

Application Number:	10750979			
Filing Date:	02-Jan-2004			
Title of Invention:	STACK PACKAGE MADE OF CHIP SCALE PACKAGES			
First Named Inventor:	Dong-Ho Lee			
Filer:	Alexander Charles Johnson/Li mei Vermilya			
Attorney Docket Number:	9903-074			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Publ. Fee- early, voluntary, or normal	1504	1	300	300
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1400	1400

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1700